L Number	Hits	Search Text	DB	I Mimo
- 1100111001	1	carpenter.in. and drennan.in. and	USPAT;	Time stamp
	1 -	easton.in. and grant.in.		2004/01/16 13:51
		eascon.in. and grant.in.	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	~
	1		IBM_TDB	
	1	carpenter.in. and drennan.in. easton.in.	USPAT;	2003/04/24 08:11
		and grant.in.	US-PGPUB;	
		'	EPO; JPO;	
	ľ		DERWENT;	
			IBM TDB	
-	52	cryogenic near3 cleaning and liquid near12	USPAT;	2004/01/16 13:52
		nitrogen	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	"0661873".PN.	USPAT	2003/04/24 08:19
-	1	"1191451".PN.	USPAT	2003/04/24 .08:20
-	1	"1978204".PN.	USPAT	2003/04/24 08:20
-	1	"1978204".PN.	USPAT	2003/04/24 08:20
_	Ī	"2259644".PN.	USPAT	2003/04/24 08:21
	1	"2347464".PN.		
_	1	"2402967".PN.	USPAT	2003/04/24 08:21
_	1	"2854360".PN.	USPAT	2003/04/24 08:21
_	1	"3182669".PN.	USPAT	2003/04/24 08:21
_	1	"3182669".PN. "3419427".PN.	USPAT	2003/04/24 08:21
_	1		USPAT	2003/04/24 08:21
1-	1	"3436263".PN.	USPAT	2003/04/24 08:21
.   =	1	"3453221".PN.	USPAT	2003/04/24 08:21
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-	1	"3536529".PN.	USPAT	2003/04/24 08:21
-	1	"3614873".PN.	USPAT	2003/04/24 08:21
	1	"3741804".PN.	USPAT	2003/04/24 08:21
-	1	"3745125".PN.	USPAT	2003/04/24 08:21
_	1	"3746023".PN.	USPAT	2003/04/24 08:21
-	1	"3774855".PN.	USPAT	2003/04/24 08:21
-	1	"3785575".PN.	USPAT	2003/04/24 08:21
_	1	"3856667".PN.	USPAT	2003/04/24 08:21
_	1	"3914132".PN.	USPAT	2003/04/24 08:21
-	1.	"3995816".PN.	USPAT	2003/04/24 08:21
_	1	"4011159".PN.	USPAT	2003/04/24 08:22
_	$ \cdot_1 $	"4025990".PN.		2003/04/24 08:22
-	$\begin{bmatrix} 1 \end{bmatrix}$	"4043140".PN.	USPAT	
_	1	"4102503".PN.	USPAT	2003/04/24 08:22
_	1	"4157016".PN.	USPAT	2003/04/24 08:22
_	1	"4157016".PN.	USPAT	2003/04/24 08:22
]_	0	cryogenic near3 cleaning and layer and	USPAT	2003/04/24 08:42
i	0	:	USPAT;	2003/04/24 08:45
		seperate	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
_	24	anyogania needa alaa	IBM_TDB	
	24	cryogenic near3 cleaning and layer and	USPAT;	2003/04/24 08:48
		separate	US-PGPUB;	
			EPO; JPO;	<u> </u>
			DERWENT;	]
			IBM_TDB	
-	88	sacrificial near3 coating and clean\$3 and	USPĀŢ;	2003/04/24 09:02
		separate	US-PGPUB;	,
			EPO; JPO;	·
			DERWENT;	
			IBM TDB	
-	1	"3676455".PN.	USPAT	2003/04/24 08:52
-	1	"3839066".PN.	USPAT	2003/04/24 08:53
-	1	"4141755".PN.	USPAT	2003/04/24 08:53
-	1	"4169088".PN.	USPAT	2003/04/24 08:53
-	1	"4177099".PN.	USPAT	2003/04/24 08:53
-	1	"4199620".PN.	USPAT	2003/04/24 08:53
1 –	1	"4241141".PN.	USPAT	2003/04/24 08:53
_	1	"4322508".PN.		
-	1	"4337299".PN.	USPAT	2003/04/24 08:53
_	1	"4349586".PN.	USPAT	2003/04/24 08:53
_	1	"4353745" DN	USPAT	2003/04/24 08:53
_	1		USPAT	2003/04/24 08:53
		"4412033".PN.	USPAT	2003/04/24 08:53

_	7	"4428994".PN.	Lugara	T0002/01/01
_	1		USPAT	2003/04/24 08:53
-	1	"4463038".PN.	USPAT	2003/04/24 08:53
-	1	"4499149".PN.	USPAT	2003/04/24 08:53
] -	1	"4590097".PN.	USPAT	2003/04/24 08:53
-	1	"4600522".PN.	USPAT	2003/04/24 08:53
-	1	"4716056".PN.	USPAT	2003/04/24 08:53
-	1	"4758622".PN.	USPAT	2003/04/24 08:53
-	1	"4777090".PN.	USPAT	2003/04/24 08:53
-	1	"4859791".PN.	USPAT	2003/04/24 08:53
_	1	"4943680".PN.	USPAT	2003/04/24 08:53
_	1	"5017237".PN.	USPAT	2003/04/24 08:53
_	1	"5024780".PN.	USPAT	
_	1	"5039745".PN.	1	2003/04/24 08:53
_	1	"5049314".PN.	USPAT	2003/04/24 08:53
_		"5061518".PN.	USPAT	2003/04/24 08:53
_		"5084370".PN.	USPAT	2003/04/24 08:54
	1	J004370 .FN.	USPAT	2003/04/24 08:54
_	$\frac{1}{1}$	"5177154".PN.	USPAT	2003/04/24 08:54
_	1	"5330788".PN.	USPAT	2003/04/24 08:54
_	1	"5352733".PN.	USPAT	2003/04/24 08:54
_	1	"5387434".PN.	USPAT	2003/04/24 08:54
_	1	"5418006".PN.	USPAT	2003/04/24 08:54
-	1	"5496642".PN.	USPAT	2003/04/24 08:54
_	1	"5631042".PN.	USPAT	2003/04/24 08:54
-	- 2	sacrificial near3 coating and sonic and	USPAT;	2003/04/24 09:05
		(semiconducter wafer)	US-PGPUB;	
		,	EPO; JPO;	
	1		DERWENT;	
			1 -	
-	6	sacrificial near3 coating and 134/\$.ccls.	IBM_TDB USPAT;	2004/01/16 12 55
		sacrificial hears coating and 134/5.ccis.	1	2004/01/16 13:53
		·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	]
			IBM_TDB	]
-	. 0	sacrificial near3 coating near22 freez\$3	USPAT;	2003/04/24 09:10
			US-PGPUB;	
ļ			EPO; JPO;	
		A. Carterina de la Carterina d	DERWENT;	
			IBM TDB	
-	0	sacrificial near3 coat\$3g near22 freez\$3	USPAT;	2003/04/24 09:11
		1 5	US-PGPUB;	2003/01/21 03:11
			EPO; JPO;	
			DERWENT;	
				. ]
_	19	sacrificial near3 coat\$3g and freez\$3	IBM_TDB USPAT;	0000/04/04 00 10
	1,5	Sacrificial hears coatssy and freezes		2003/04/24 09:12
			US-PGPUB;	İ
			EPO; JPO;	
		·	DERWENT;	į į
		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
-	42	clean\$3 and freez\$3 and sonic and wafer	USPĀT;	2003/04/24 09:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	]		IBM TDB	
-	12	peel\$3 near12 adhesive near22 (contaminant	USPAT;	2003/04/24 09:21
		foreign near3 matter) and wafer	US-PGPUB;	=====================================
		J Con y Carrow Helica	EPO; JPO;	
		· ·	DERWENT;	
			IBM TDB	
-	3206	particle near3 removal and (adhesive	_ :	2002/04/24 00 02
-	5200	adhere adherent)	USPAT;	2003/04/24 09:23
1		dancie adherent)	US-PGPUB;	·
1	'		EPO; JPO;	
1			DERWENT;	
· _	050		IBM_TDB	
-	252	particle near3 removal and (adhesive	USPAT;	2003/04/24 09:24
		adhere adherent) and 134/\$.ccls.	US-PGPUB;	
			EPO; JRO;	
			DERWENT;	·
			IBM TDB	
	1	"3080263".PN.	USPAT	2003/04/24 09:30
-	1	"3717897".PN.	USPAT	2003/04/24 09:30
<b>-</b>	1	"3754991".PN.	USPAT	2003/04/24 09:30
-	1	"4156619".PN.	USPAT	2003/04/24 09:30
		· · · · · · · · · · · · · · · · · · ·	~~L111	-000/04/24 U3:30

·	1	"5320706".PN.	LUGDAM	1 6 6 6 6 10 1 10 1 10 1
_	86035	polymer and adhesive and (heat energy)	USPAT	2003/04/24 09:30
	00033	polymer and adhesive and (heat energy)	USPAT;	2003/04/25 09:40
			US-PGPUB;	i
			EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
_	198	polymer and adhesive and (heat energy) and	USPAT;	2003/04/25 10:39
		134/\$.ccls.	US-PGPUB;	2003/04/23 10.33
			EPO; JPO;	
			DERWENT;	
1	26	malaman and albert	IBM_TDB	
	20	F - J - was danced to and theat energy, and	USPAT;	2003/04/25 10:39
		134/\$.ccls. and wafer	US-PGPUB;	
			EPO; JPO;	•
			DERWENT;	
			IBM TDB	
-	36130	adhesive and curable polymer\$3 and clean\$3	USPĀT;	2003/04/25 12:58
		and (wafer semiconducter)	US-PGPUB;	2003/04/23 12.30
		,	EPO; JPO;	
		•	DERWENT;	
_	27984	adhaniza and supplied to	IBM_TDB	
	2/984	adhesive and curable polymer\$3 and clean\$3	USPAT;	2003/04/25 12:59
1		near22 (wafer semiconducter) and	US-PGPUB;	
		234/\$.ccls.	EPO; JPO;	
		,	DERWENT;	
		·	IBM TDB	
-	0	adhesive and curable near2 polymer\$3 and	USPAT;	2003/04/25 12:59
1		clean\$3 near22 (wafer semiconducter) and	US-PGPUB;	2003/04/23 12:59
		234/\$.ccls.		:
ľ		23177.0013.	EPO; JPO;	1
			DERWENT;	1
			IBM_TDB	ļ
-	1	adhesive and curable near2 polymer\$3 and	USPAT;	2003/04/25 13:02
ľ		clean\$3 near22 (wafer semiconducter) and	US-PGPUB;	
		134/\$.ccls.	EPO; JPO;	
*			DERWENT;	
			IBM TDB	
-	50	adhesive and curable near2 polymer\$3 and	USPAT;	2003/04/25 13:04
		clean\$3 near22 (wafer semiconducter)	· ·	2003/04/25 13:04
		ordanys mearzz (warer semiconducter)	US-PGPUB;	
	1		EPO; JPO;	
	1	•	DERWENT;	
ľ	1 . 1		IBM TDB	
_	1	"3080263".PN.	USPAT	2003/04/26 06:57
-	1	"3717897".PN.	USPAT	2003/04/26 06:57
-	1	"3754991".PN.	USPAT	2003/04/26 07:00
-	1	"4156619".PN.	USPAT	2003/04/26 07:00
-	1	"5320706".PN.	USPAT	2003/04/26 07:00
_	0	semiconducter near3 wafer and ultrasonic	l	1
		near3 clean\$3 and water	USPAT;	2003/04/26 07:20
		oroning and waret	US-PGPUB;	
			EPO; JPO;	·
			DERWENT;	l
1			IBM_TDB	
-	0	semiconducter near3 wafer and ultrasonic	USPAT;	2003/04/26 07:21
		near3 clean\$3 and water and 134/1.ccls.	US-PGPUB;	
			EPO; JPO;	
1	1		DERWENT;	
1			IBM TDB	
-	48	semiconductor near3 wafer and ultrasonic	USPAT;	2003/04/26 07:21
	"	near3 clean\$3 and water and 134/1.ccls.		2003/04/26 0/:21
		mours organiss and water and 134/1.CCls.	US-PGPUB;	
i		·	EPO; JPO;	
			DERWENT;	
	1		IBM TDB	·
-	38	semiconductor near3 wafer and ultrasonic	USPAT	2003/04/26 07:51
		near3 clean\$3 and water and 134/1.ccls.		- 10,01,20 0,.01
-	1	134/\$.ccls. and curable near1 polymer and	USPAT;	2003/04/26 08:12
		(wafer semiconductor) and coat\$3 and		2003/04/20 08:12
		(contaminate clean\$3 adhere adhesive)	US-PGPUB;	
		(oomeaminate creamys adhere adhesive)	EPO; JPO;	1
			DERWENT;	1
L	L		IBM TDB	

	150		···	
-	158	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate	USPAT; US-PGPUB;	2003/04/26 08:13
		clean\$3 adhere adhesive)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	Taranta marr porjust and (warer	USPAT;	2003/04/26 08:13
	İ	semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and clean\$3.ti.	US-PGPUB;	
		creanys adhere adhesive, and creanss.cr.	EPO; JPO; DERWENT;	
			IBM TDB	
-	1	i remaind a state of the state	USPAT;	2003/04/26 08:14
		semiconductor) and coat\$3 and (contaminate	US-PGPUB;	
		clean\$3 adhere adhesive) and (removal	EPO; JPO;	]
		clean\$3).ti.	DERWENT;	
	130	curable nearl polymer and (wafer	IBM_TDB USPAT;	2003/04/26 08:23
	1	semiconductor) and coat\$3 and (contaminate	US-PGPUB;	2003/04/26 08:23
		clean\$3 adhere adhesive) and (adhesive	EPO; JPO;	
		removal clean\$3).ti.	DERWENT;	
			IBM_TDB	
_	361	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3	USPAT;	2003/04/26 08:24
		adhere adhesive)	US-PGPUB; EPO; JPO;	
		dancie danesive)	DERWENT;	
			IBM TDB	
-	361	curable nearl polymer and (face skin	USPAT;	2003/04/26 08:30
		pore) and coat\$3 and (contaminate clean\$3	US-PGPUB;	
		adhere adhesive) and (adhesive removal	EPO; JPO;	
İ		clean\$3 skin face pore).ti.	DERWENT;	
	0	curable near1 polymer and (face skin	IBM_TDB USPAT;	2003/04/26 08:31
		pore) and coat\$3 and (contaminate clean\$3	US-PGPUB;	2003/04/20 00.31
		adhere adhesive) and (adhesive removal	EPO; JPO;	
		clean\$3 skin face pore).ti. and pore near2	DERWENT;	·
	0	cleaning	IBM_TDB	
_		curable near1 polymer and pore near2 cleaning	USPAT;	2003/04/26 08:31
		Citaling	US-PGPUB; EPO; JPO;	
		,	DERWENT;	
	İ		IBM_TDB	
_	84	pore near2 cleaning	USPAT;	2003/04/26 08:44
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	2	pore near2 cleaning and (polyimide lacquer	USPAT;	2003/04/26 08:47
		latex rubber near1 cement)	US-PGPUB;	
	Ì	·	EPO; JPO;	
			DERWENT;	
-	3684	polyimide and adhesive and cleaning	IBM_TDB USPAT;	2003/04/26 08:47
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	3684	polyimide and adhesive and cleaning	IBM TDB	2002/04/25 22 :=
	3004	sacrificail and coating	USPAT;	2003/04/26 08:48
		Substituted and country	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	244	polyimide and adhesive and cleaning and	USPĀT;	2003/04/26 08:48
		sacrificial and coating	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	244	polyimide and adhesive and cleaning and	USPAT;	2003/04/26 08:48
		sacrificial and coating and surface	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	,
<u> </u>	L		IBM_TDB	

-	20		USPAT;	2003/04/26 08:49
•		sacrificial and coating and surface and	US-PGPUB;	
		curable	EPO; JPO;	
	Ì		DERWENT;	
			IBM TDB	
-	18	polyimide and adhesive and cleaning and	USPAT;	2003/04/26 08:49
Ì		sacrificial and coating and surface and	US-PGPUB;	2000,01,20 00.49
		curable and polymer	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	"2495729".PN.	USPAT	2003/04/26 00:26
_	1	"3063873".PN.	1	2003/04/26 09:36
_	1		USPAT	2003/04/26 09:36
_	1	"3404134".PN.	USPAT	2003/04/26 09:36
1_	1	"3634278".PN.	USPAT	2003/04/26 09:36
_	1 1		USPAT	2003/04/26 09:36
_	2	"4053666".PN.	USPAT	2003/04/26 09:36
	2	"20020189635"	USPAT;	2003/04/26 09:50
			US-PGPUB;	
			EPO; JPO;	
	!		DERWENT;	
			IBM TDB	
-	38370		USPAT;	2003/04/26 10:03
		particulate matter and polymer and layer	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
1	1 '		IBM TDB	
-	0	sonic near5 clean\$3 and dislodge near6	USPAT;	2003/04/26 10:03
		particulate near3 matter and polymer and	US-PGPUB;	2003/04/20 10:03
		layer .	EPO; JPO;	!
İ				'
			DERWENT;	
_	0	sonic near5 clean\$3 and dislodge near6	IBM_TDB	0000 (01 (05 10 10
	1	(particulate matter) and disloge hearb	USPAT;	2003/04/26 10:03
		(particulate matter) and polymer and layer	US-PGPUB;	
			EPO; JPO;	'
			DERWENT;	
			IBM_TDB	
_	68	sonic near5 clean\$3 and polymer and layer	USPAT;	2003/04/26 10:03
			US-PGPUB;	
		·	EPO; JPO;	
	-		DERWENT;	'
			IBM TDB	
-	68	sonic near5 clean\$3 and polymer and layer	USPĀT;	2003/04/26 10:27
			US-PGPUB;	
	,		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	31	(ultrasonic sonic) near5 clean\$3 and	USPAT;	2003/04/26 10:28
		sacrificial near3 (coating layer polymer)	US-PGPUB;	1 2000, 01, 20 10.20
]		and clean\$3	EPO; JPO;	
			DERWENT;	<u> </u>
			IBM TDB	
-	2	5690749.pn.	USPAT;	2003/09/18 09:39
	-	,	1	2003/09/18 09:39
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1	"3080263".PN.	IBM_TDB	
_	1		USPAT	2003/09/18 09:35
_		"3717897".PN.	USPAT	2003/09/18 09:37
_	1	"3754991".PN.	USPAT	2003/09/18 09:37
<u> </u>	1	"4156619".PN.	USPAT	2003/09/18 09:37
_	1	"5320706".PN.	USPAT	2003/09/18 09:37
-	573	strippable near2 coating	USPAT;	2003/09/18 09:43
			US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
· 1			IBM TDB	
-	5	strippable near2 coating and (megasonic	USPAT;	2003/09/18 09:41
		utrasonic sonic)	US-PGPUB;	
1			EPO; JPO;	
,	1		DERWENT;	
		i .	IBM TDB	
			TD17 1DD	

36   Strippeble near2 coating and contaminant   US_ATT   US_FOUR; Reo, JPC; US_FOUR; Re					
### 10960   ### 10	-	36	strippable near2 coating and contaminant		2003/09/18 09:43
DERMENT;   DERMENT;					
Strippable near2 (film coating) and contaminant		Ì		The state of the s	·
Second	,				
Contaminant	_	56	strippable near2 (film coating) and		2003/09/18 10:50
2					2003/03/18 10:50
2					
2   ultrasonic mear33 encapsulat\$4 near33   USPĀT; CONTAMINANT   USPĀCUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; DERWENT; LIEM TIDB   USPĀT; US-PGPUB; EPG; JPG; USPĀT; US-PGPUB; EPG; JPG; USPĀT			·	1	
Contaminant					
See		2			2003/09/18 10:51
DERMENT;   IBM TOB			contaminant		
18M TDB   18FAT;   18FAT;   18FAT;				I .	
-		·			
Content   Cont	_	564	ultrasonic near33 encapsulat\$4		2003/09/18 10:51
-			Choapbaracy.		2003/03/18 10.31
-			. ,		
10960   encapsulat\$4 with contaminant   108   1003/09/18   10:55   100					
134/.ccls.		Ì			
SEO, JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFA	_	2			2003/09/18 10:52
DERWENT; IM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:42 USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TOB US			134/.ccls.	US-PGPUB;	
TBM TDB					
30   ultrasonic near33 encapsulat\$4 and wafer   USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; EPO; JPO; DERWENT; IBM TDB USFAT; USFACEUB; USFAT;					
US-PGPUB; EPP, JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US	-	- 30	ultrasonic mear33 encapsulat\$4 and wafor		2003/00/10 10:54
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DERMENT;   IBM TDB   USPAT;   US-PGFUB;   EPO; JPO;   DERMENT;   IBM TDB   USPAT;   US-PGFUB;   EPO; JPO;   DERMENT;   IBM TDB   USPAT;   US-PGFUB;   EPO; JPO;   DERMENT;   IBM TDB   USPAT;   US-PGFUB;   EPO; JPO;   DERMENT;   USPAT;					·
- 302199 encapsulat\$4 contaminant					
10960   encapsulat\$4 and contaminant   US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;					
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO	_	302199	encapsulat\$4 contaminant	USPAT;	2003/09/18 10:55
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT USPAT USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:42 USPAT 2003/09/18 13:42 USPAT 2003/09/18 13:45 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT; USPAT; USPAGPUB; EPO; JPO; DERWENT; USPAGPUB; EPO; JPO; DERWENT; USPGPUB; EPO; JPO; DERWENT; USPAGPUB; EPO; JPO; DERWENT; EPO; JPO; DERW				US-PGPUB;	
- 10960 encapsulat\$4 and contaminant USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:45 USPAT; USPAT					
- 10960 encapsulat\$4 and contaminant USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT USPĀT USPĀT USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:45 USPĀT USPĀT 2003/09/18 13:45 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT USPĀT U					. [
Solution	_	10960	encapsulat\$4 and contaminant	_	2002/00/10 10 55
B07   encapsulat\$4 with contaminant   EPO; JPO; DERWENT; IBM TDB   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPĀT		10300	encapoutaty4 and contaminant	1	2003/09/18 10:55
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; USPAT USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:45 USPAT;					
BM TDB					
106   encapsulat\$4 with contaminant and (sonic ultrasonic megasonic)   US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT 2003/09/18 13:41					
106   encapsulat\$4 with contaminant and (sonic ultrasonic megasonic)   EPO; JPO; DERWENT; TBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT 2003/09/18 13:41	_	807	encapsulat\$4 with contaminant	1	2003/09/18 10:55
106   encapsulat\$4 with contaminant and (sonic ultrasonic megasonic)   DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:42 USPĀT; USPĀ					
106   encapsulat\$4 with contaminant and (sonic ultrasonic megasonic)   IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB USPĀT USPĀT USPĀT 2003/09/18 13:41					
106 encapsulat\$4 with contaminant and (sonic ulspat; ultrasonic megasonic)  2 ("4,178,188").PN.  2 ("4,178,188").PN.  1 "2009278".PN.  1 "2009278".PN.  2 "4476177".PN.  375 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  57627 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  10			•		
Us-pgpus;   EPO; JPO;   DERWENT;   IBM TDB   UspAT   UspAT   UspAT   2003/09/18 13:41   UspAT   2003/09/18 13:45   UspAT   UspAT   2003/09/18 13:45   UspAT   UspAT   2003/09/18 13:45   UspAT   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   UspAT   2003/09/18 13:45   UspAT   2003/09/18 13:45   UspAT   UspAT   2003/09/18 13:45   UspAT   UspAT   UspAT   2003/09/18 13:45   UspAT   UspA	·	106	encapsulat\$4 with contaminant and (sonic		2002/00/10 11.27
EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:41 USPĀT 2003/09/18 13:42 USPĀT 2003/09/18 13:45 USPĀT 2003/09/18 13:45 USPĀT 2003/09/18 13:45 USPĀT; USPĀT 2003/09/18 13:45 USPĀT; USPĀT; USPĀPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀPUB; EPO; JPO; DERWENT; IBM TDB USPĀT; USPĀPUB; EPO; JPO; DERWENT; USPĀPUB; EPO; JPO; DERWENT; USPĀPUB; EPO; JPO; DERWENT;			ultrasonic megasonic)		2003/09/18 11:2/
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; USPAT			<i>y</i>		
- 2 ("4,178,188").PN. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT 2003/09/18 13:41 - 1 "4806277".PN. USPAT 2003/09/18 13:41 - 1 "4476177".PN. USPAT 2003/09/18 13:41 - 1 "5320706".PN. USPAT 2003/09/18 13:42 - 375 (apply application) near122 film with heat\$3 with strip\$4 USPAT;					'
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; DERWENT; heat\$3 with strip\$4 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; ISPĀT; US-PGPUB; EPO; JPO; DERWENT; ISPĀT; US-PGPUB; EPO; JPO; DERWENT;			494 450 4000		
EPO; JPO; DERWENT; IBM_TDB USPAT USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:41 USPAT 2003/09/18 13:42 USPAT 2003/09/18 13:45 USPAT 2003/09/18 13:45 USPAT 2003/09/18 13:45 USPAT 2003/09/18 13:45 USPAT 2003/09/18 13:45 USPAT; USPAT	-	2	("4,178,188").PN.		2003/09/18 11:27
DERWENT; IBM_TDB USPAT; heat\$3 with strip\$4  57627  (apply application) near122 film with heat\$3 with strip\$4  (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  57627  (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.					
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1 "2009278".PN. "4806277".PN. "4476177".PN. "5320706".PN. (apply application) near122 film with heat\$3 with strip\$4  57627  [apply application) near122 film with heat\$3 with strip\$4  [apply application) near122 film with heat\$3 with strip\$4  [apply application) near122 film with heat\$3 with strip\$4  [apply application) near122 film with heat\$3 with strip\$4  [apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  [apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  [apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.					
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1 "4476177".PN. "5320706".PN. (apply application) near122 film with heat\$3 with strip\$4  57627 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  USPAT USPAT USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;			"4806277".PN.		
1 375 (apply application) near122 film with heat\$3 with strip\$4 USPAT; U	-	1	"4476177".PN.		
- S7627 (apply application) near122 film with heat\$3 with strip\$4 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; heat\$3 with strip\$4 an 134/.ccls. US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	-			1	
57627 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	-	375	(apply application) near122 film with		
57627 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;			heat\$3 with strip\$4	. 1	
- 57627 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls. IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;			·		5
57627 (apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.  USPAT; US-PGPUB; EPO; JPO; DERWENT;				- I	
heat\$3 with strip\$4 an 134/.ccls.  US-PGPUB; EPO; JPO; DERWENT;	_	57627	(apply application) near122 film with		2003/00/10 14 10
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-	1	"2009278".PN.	USPAT	2003/09/18 18:24	
-	1	"3166445".PN.	USPAT	2003/09/18 18:24	
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~	1	"3733710".PN.	USPAT	2003/09/18 18:24	
1 -	1	"4186032".PN.	USPAT	2003/09/18 18:24	
_	1	"4266982".PN.	USPAT	2003/09/18 18:24	
-	1 1	"4409034".PN.	USPAT	2003/09/18 18:24	
	1	"4586962".PN.	USPAT	2003/09/18 18:24	
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